EPLY UNDER 37 CFR §1.116
EXPEDITED PROCEDURE
ART UNIT 2826

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Yian-Liang Kuo, et al.	§	Attorney Docket No.: 2002-0978/24061.43
	§	
	§	Customer No.: 42717
Application No.: 10/680,664	§	
	§	Group Art Unit: 2826
Filed: October 7, 2003	§	
	§	Examiner: Williams, Alexander O.
For: Integrated Circuit Package Bond Pad Having Plurality of Conductive Members	§	
	§	Confirmation No.: 5418
	§	

Commissioner for Patents
Mail Stop AF
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO FINAL OFFICE ACTION MAILED OCTOBER 25, 2007

In response to the Final Office Action of October 25, 2007, entry of the following comments into the record of the above-identified application is respectfully requested. No additional fees are believed to be due in connection with this filing. Should any additional fees be required, please charge such fees to Haynes & Boone LLP Deposit Account No. 08-1394.

Listing of Claims begins on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.